FEATURES

- 10-Bit Resolution
- Sampling Rates from <1 kHz to 1.5 MHz
- . DNL better than 1/2 LSB (typ) up to 1.5 MHz
- Very Low Power CMOS 30 mW (typ)
- Power Down: Lower Consumption 3 mW (typ)
- Interface to any Input Range between GND and VDD
- No S/H Required for Analog Signals less than 100 kHz
- No S/H Required for CCD Signals less than 1.5 MHz
- Single Power Supply (4 to 6.5 Volts)
- Latch-Up Free
- High ESD Protection: 4000 Volts Minimum
- 24 Pin CDIP, PDIP & SOIC Packages Available

BENEFITS

- Reliable Operation
- Reduced Board Space (Small Package)
- Reduced External Parts, No Sample/Hold Needed
- Suitable for Battery & Power Critical Applications
- Designer Can Adapt Input Range 8: Scaling

APPLICATIONS

- μP/DSP Interface and Control Applications
- High Resolution Imaging Scanners, Copiers, Facsimile
- Radar Pulse Analysis
- Low Power A/D Applications

3

GENERAL DESCRIPTION

The MP8795 is a flexible, easy to use, precision 10-bit A/D Converter that operates over a wide range of input and sampling conditions. The MP8795 can operate with conversion operation or continuous "pipeline" operation for sampling rates up to 1.5 MHz. The elimination of the S/H, requirements, very low power, and small package size offer the designer a low cost solution. No sample and hold is required for charge couple device applications, up to 1.5 MHz, or multiplexed input applications when the signal source bandwidth is limited to 100 kHz. The input architecture of the MP8795 allows direct interface to any analog input range between AGND and AV_{DD} (0 to 2 V, 1 to 4 V, 0 to 5 V, etc.). The user simply sets V_{REF(+)} and V_{REF(-)} to encompass the desired input range.

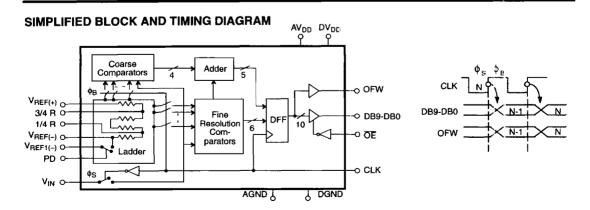
Scaled reference resistor taps 1/4 R and 3/4 R allow for

customizing the transfer curve. Digital outputs offer tri-state operation and all digital pins are CMOS and "TL compatible.

The Micro Power Systems' MP8795 uses a two step technique. The first segment converts the 4 MSBs and consists of 15 autobalanced comparators, latches, an encoder, and buffer storage registers. The second segment converts the remaining 6 LSBs.

When the power down input is "high", the data outputs DB9 to DB0 hold the current values and $V_{REF(-)}$ is disconnected from $V_{REF1(-)}$. The power consumption during the power down mode is approximately 3mW.

Specified for operation over the commercial / industrial (-40 to +85°C) and military (-55 to +125°C) temper ature ranges, the MP8795 is available in Plastic (PDIP) and Ceramic (CDIP) dual-in-line, and Surface Mount (SOIC) packages.



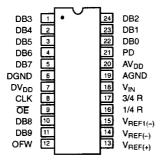


ORDERING INFORMATION

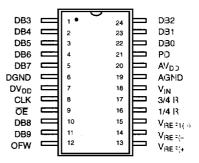
Package Type	Temperature Range	Part No.	DNL (LSB)	INL (LSB)	
Plastic Dip	-40 to +85°C	MP8795AN	±1	±1 1/2	
SOIC	-40 to +85°C	MP8795AS	±1	土1 1/2	
*Ceramic Dip	-55 to +125°C	MP8795SD	±1	±1 1/2	
*Ceramic Dip	-55 to +125°C	MP8795SD/883	±1	±1 1/2	

^{*}Contact Factory for availability

PIN CONFIGURATIONS



24 Pin CDIP, PDIP (0.300") DN24, NN24



24 Pin SOIC (Jedec, 0.300") S24

PIN OUT DEFINITIONS

PIN NO.	NAME	DESCRIPTION				
1	DB3	Data Bit 3 Output				
2	DB4	Data Bit 4 Output				
3	DB5	Data Bit 5 Output				
4	DB6	Data Bit 6 Output				
5	DB7	Data Bit 7 Output				
6	DGND	Digital Ground				
7	DV _{DD}	Digital V _{DD}				
8	CLK	Clock Input				
9	ŌĒ	Output Enable (Active Low)				
10	DB8	Data Bit 8 Output				
11	DB9	Data Bit 9 Output (MSB)				
12	OFW	Overflow Output				

PIN NO.	NAME	DESCRIPTION			
13	V _{REF(+)}	Upper Reference Voltage			
14	V _{REF(-)}	Lower Reference Voltage			
15	V _{REF1(-)}	Lower Reference Voltage			
16	1/4 R	Reference Ladder Tap @ 1/4 FS			
17	3/4 R	Reference Ladder Tap @ 3/4 FS			
18	VIN	Analog Signal Input			
19	AGND	Analog Ground			
20	AV _{DD}	Analog V _{DD}			
21	PD	Power Down			
22	DB0	Data Bit 0 Output (LSB)			
23	DB1	Data Bit 1 Output			
24	DB2	Data Bit 2 Output			



ELECTRICAL CHARACTERISTICS TABLE

Unless Otherwise Specified: $AV_{DD} = DV_{DD} = 5 \text{ V}$, $F_S = 1 \text{ MHz}$ (50% Duty Cycle),

 $V_{REF(+)} = 4.6$, $V_{REF(-)} = AGND$, $T_A = 25^{\circ}C$

			25°C		Tmin to	Tmax		
Parameter	Symbol	Min	Тур	Max	Min	Max	Units	Test Conditions/Comments
KEY FEATURES								
Resolution		10					Bits	
Sampling Rate	Fs	.001		1			MHz	For Rated Performance
ACCURACY ²						_		
Differential Non-Linearity	DNL		±3/4	<u>±</u> 1			LSB	
Integral Non-Linearity	INL			±1 1/2			LSB	Best Fit Line
Zero Scale Error	EZS		+1.00				LSB	(Max INL – M·n INL)/2 Reference fro 'n W _{REF(+)} to V _{REF} (
Full Scale Error	EFS		-2.5				LSB	The (F)
REFERENCE VOLTAGES					,			
Positive Ref. Voltage	V _{REF(+)}			AV _{DD}			v	
Negative Ref. Voltage	V _{REF(-)}	AGND					V	
Differential Ref. Voltage ⁵	V _{REF}	0.5		AV_{DD}			٧	
Ladder Resistance	_ R _L	525	675	900			Ω	
Ladder Temp. Coefficient ¹	Втсо		2000 12				ppm/°C	
Ladder Switch Resistance ¹ Ladder Switch Off Leakage ¹			50				Ω nA	
-	lilkg-sw							
ANALOG INPUT ¹								
Input Bandwidth			100				kHz	1 LSB Error
Input Voltage Range ⁷	V _{IN}	V _{REF(-)}		V _{REF(+)}			٧	
Input Capacitance ³	CIN	(/	60				pF	
Aperture Delay	t _{AP}		35				ns	
DIGITAL INPUTS								
Logical "1" Voltage	V _{IH}	2.0					v	
Logical "0" Voltage	V _{IL}			8.0			V	
Leakage Currents	IIN							V _{IN} =DGND to D\'_DD
CLK				±100			μΑ	
PD, OE (Internal Res to DGND)		-5	_	30			μA	
Input Capacitance			5				pF	
Clock Timing (See Figure 1.)1	١.							
Clock Period Rise & Fall Time ⁴	t _S	500		10			ns ns	
"High" Time ⁶	t _R , t _F	250		500,000			ns	
"Low" Time ⁶	ts	150		500,000			ns	Functional
DIGITAL OUTPUTS								C _{OUT} =15 pF
Logical "1" Voltage	Vou	DV _{DD} -0.5					v	I _{LOAD} ≈ 2 mA
Logical "0" Voltage	VOL			0.4			v	ILOAD = 4 mA
Tristate Leakage	loz	0		<u>+</u> 5			μA	$V_{OUT} = 0$ to V_{DD}
Data Hold Time (See Figure 1.)1	tHLD		30				ns	
Data Valid Delay ¹	t _{DL}	l	70				ns	



ELECTRICAL CHARACTERISTICS TABLE (CONT'D)

Parameter	Symbol	Min	25°C Typ	Max	Tmin to Min	Tmax Max	Units	Test Conditions/Comments
DIGITAL OUTPUTS (CONT'D)								C _{OUT} =15 pF
Data Enable Delay ¹ Data Tristate Delay ¹ Clock to PD Set-up Time ¹ Clock to PD Hold Time ¹ Power Down Delay ¹ Power Up Delay ¹	tDEN tDHZ tCLKS1 tCLKH1 tPD tPU		25 15	400 600 300 200			ns ns ns ns ns	
POWER SUPPLIES ⁸ Power Down (I _{DD}) Operating Voltage (AV _{DD} , DV _{DD}) Current (AV _{DD} + DV _{DD})	I _{DDOWN} V _{DD} I _{DD}	4	0.6 5 6	1.2 6.5 10			mA V mA	V _{IN} = 2 V

NOTES:

- Guaranteed. Not tested.
- Tester measures code transition voltages by dithering the voltage of the analog input (V_{IN}). The difference between the measured code width and the ideal value (V_{REF}/1024) is the DNL error (see Figure 3.). The INL error is the maximum distance (in LSBs) from the best fit line to any transition voltage (See Figure 7.).
- See VIN input equivalent circuit (see Figure 9.).
- Clock specification to meet aperture specification (t_{AP}). Actual rise/fall time can be less stringent with no loss of accuracy. Specified values guarantee functional device. Refer to other parameters for accuracy.
- System can clock MP8795 with any duty cycle as long as all timing conditions are met.
- Input range where input is converted correctly into binary code. Input voltage outside specified range converts to zuro or full scale output.
- DV_{DD} and AV_{DD} are connected through the silicon substrate. Connect together at the package.

Specifications are subject to change without notice

ABSOLUTE MAXIMUM RATINGS (1, 2, 3) (Ta = +25°C unless otherwise noted)

V _{DD} (to GND)	Storage Temperature65 to +150°C
V _{REF(+)} & V _{REF(-)} GND -0.5 to V _{DD} +0.5 V	Lead Temperature (Soldering 10 seconds) +300°C
V _{IN} GND -0.5 to V _{DD} +0.5 V	Package Power Dissipation Rating to 75°C
All Inputs GND -0.5 to V _{DD} +0.5 V	CDIP, PDIP, SOIC 1000mW
All Outputs GND -0.5 to V _{DD} +0.5 V	Derates above 75°C 14mW/°C

- Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation at or above this specification is not implied. Exposure to maximum rating
- conditions for extended periods may affect device reliability.

 Any input pin which can see a value outside the absolute maximum ratings should be protected by Schottky diode clamps (HP5082-2835) from input pin to the supplies. All inputs have protection diodes which will protect the device from short V_{DD} refers to AV_{DD} and DV_{DD}. GND refers to AGND and DGND.



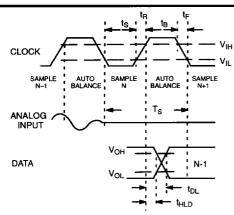


Figure 1. MP8795 Timing Diagram

THEORY OF OPERATION

Analog-to-Digital Conversion

The MP8795 converts analog voltages into 1024 digital codes by encoding the outputs of 15 coarse and 67 fine comparators. Digital logic is used to generate the overflow bit. The conversion is synchronous with the clock and it is accomplished in 2 clock periods.

The reference resistance ladder is a series of 1025 resistors. The first and the last resistor of the ladder are half the value of the others so that the following relations apply:

 $R_{REF} = 1024 * R$ $V_{REF} = V_{REF(+)} - V_{REF(-)} = 1024 * LSB$ The clock signal generates the two internal phases, ϕ_B (CLK high) and ϕ_S (CLK low = sample) (See Figure 2.). The rising edge of the CLK input marks the end of the sampling phase (ϕ_S). Internal delay of the clock circuitry will delay the actual instant

when ϕ_S disconnects the latches from the comparators. This delay is called aperture delay (t_{AP}).

The coarse comparators make the first pass conversion and selects a ladder range for the fine comparators. The fine comparators are connected to the selected range during the next ϕ_B phase.

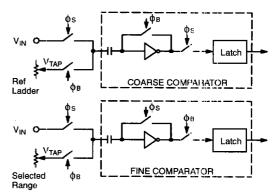


Figure 2. MP8795 Comparators

AIN Sampling, Ladder Sampling, and Conversion Timing

Figure 3. shows this relationship as a timing chart. A_{IN} sampling, ladder sampling and output data relationships are shown for the general case where the levels which drive the ladder need to change for each sampled A_{IN} time point. The ladder is referenced for both last A_{IN} sample and $\frac{1}{1000}$ and $\frac{1}{1000}$ $\frac{1}{1000}$ Also note than 1 LSB, one of the samples must be discarded. Also note that the clock low period for the discarded A_{IN} can be reduced to the minimum t_S time of 150 ns.

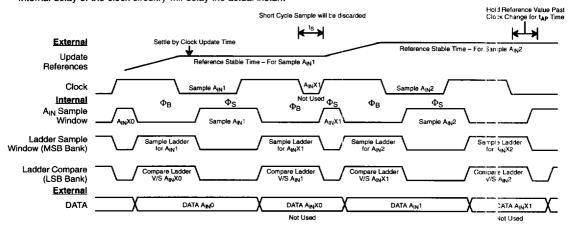


Figure 3. AIN Sampling, Ladder Sampling & Conversion Timing



Accuracy of Conversion: DNL and INL

The transfer function for an ideal A/D converter is shown in Figure 4.

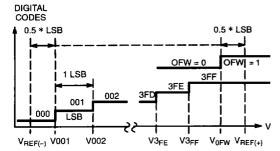


Figure 4. Ideal A/D Transfer Function

The overflow transition (VOFW) takes place at:

$$V_{IN} = V_{OFW} = V_{REF(+)} - 0.5 * LSB$$

The first and the last transitions for the data bits take place at:

$$V_{IN} = V001 = V_{REF(-)} + 0.5 * LSB$$

$$V_{IN} = V3_{FF} = V_{REF(-)} - 1.5 * LSB$$

$$LSB = V_{REF} / 1024 = (V3_{FF} - V001) / 1022$$

Note that the overflow transition is a flag and has no impact on the data bits.

In a "real" converter the code-to-code transitions don't fall exactly every $V_{\rm REF}/1024$ volts.

A positive DNL (Differential-Non-Linearity) error means that the real width of a particular code is larger than 1 LSB. This error is measured in fractions of LSB's.

A Max DNL specification guarantees that ALL code widths (DNL errors) are within the stated value. A specification of Max DNL = \pm 0.5 LSB means that all code widths are within 0.5 and 1.5 LSB. If V_{REF} = 4.608 V then 1 LSB = 4.5 mV and every code width is within 2.25 and 6.75 mV.

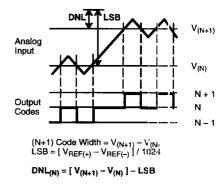


Figure 5. DNL Measurement On Production Tester

The formulas for Differential Non-linearity (DNL), Integral Non-Linearity (INL) and zero and full scale errors (E_{ZS}, E_{ES}) are:

DNL (3FE) =
$$V3_{FF} - V3_{FE} - LSB$$

$$E_{FS}$$
 (full scale error) = $V_{REF(+)} - 1.5 \times LSB - V3_{FF}$

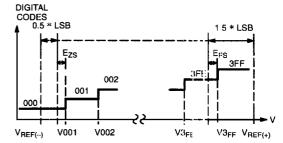


Figure 6. Real A/D Transfer Curve

Figure 7. shows the zero scale and full scale error terms.



Figure 7. gives a visual definition of the INL error. The chart shows a 3 bit converter transfer curve with greatly exaggerated DNL errors to show the deviation of the real transfer curve from the ideal one.

After a tester has measured all the transition voltages, the computer draws a line parallel to the ideal transfer line. By definition the Best Fit Line makes equal the positive and the negative INL errors. For example, an INL error of –1 to +2 LSB's relative to the Ideal Line would be ± 1.5 LSB's relative to the Best Fit Line.

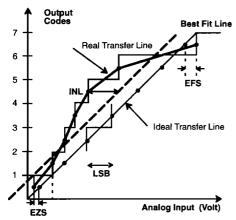
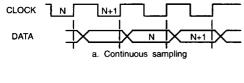


Figure 7. INL Error Calculation (Exaggerated for Visualization)

Clock and Conversion Timing

A system will clock the MP8795 continuously or it will give clock pulses intermittently when a conversion is desired. The timing of *Figure 8a* shows normal operation, while the timing of *Figure 8b* keeps the MP8795 in balance and ready to sample the analog input.



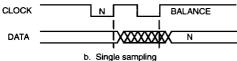


Figure 8. Relationship of Data to Clock

Analog Input

The MP8795 has very flexible input range characteristics. The user may set $V_{REF(+)}$ and $V_{REF(-)}$ to two fixed voltages and then varies the input DC and AC levels to match the V_{REF} range. However, a more common use of this flexibility is to first design the analog circuitry and then to adjust the reference voltages to include the analog input range. One advantage is that this approach may eliminate the need for external ς ain and offset adjust circuitry which may be required by fixed input range A/Ds. It is good design practice to proceed with thise steps:

- 1) Estimate V_{REF} range.
- 2) Design analog circuitry.
- Prototype analog circuitry and debug with ADC clocked.
- 4) Adjust Ver range.

Good driving capabilities (low resistance, high current) of circuitry driving the flash analog input are guarenteed to optimize the MP8795 performance. *Figure 9.* shows the equivalent circuit for A_{IN}.

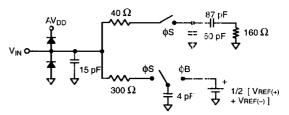


Figure 9. Analog Input Equivalent Circuit

Reference Voltages

The input/output relationship is a function of V_{BEE}:

$$A_{IN} = V_{IN} - V_{REF(-)}$$

$$V_{REF} = V_{REF(+)} - V_{REF(-)}$$
DATA = 1023 * (A_{IN}/V_{REF})

A system can increase total gain by reducing V_{REF}

Digital Interfaces

The logic encodes the outputs of the comparators into a binary code and latches the data in a D-type tlip-flop for output. The input \overline{OE} controls the output buffers in an asynchronous mode.

ŌĒ	OFW	DB9 - DB0			
1	Valid	High Z			
0	Valid	Valid			

Table 2. Output Enable Logic



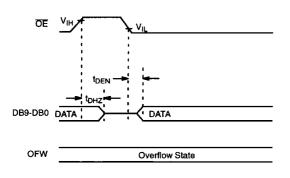


Figure 10. Output Enable/Disable Timing Diagram

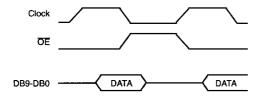


Figure 11. Preferred Output Control

Figure 11. shows the preferred output control where \overline{OE} and clock are opposite phase. This provides a quiet time at the end of the A_{IN} sample phase.

The functional equivalent of the MP8785 Figure 12.) is composed of:

- Delay stage (t_{AP}) from the clock to the sampling phase (\$\phi_s\$).
- An ideal analog switch which samples V_{IN}.
- An ideal A/D which tracks and converts V_{IN} with no delay.
- A series of two DFF's with specified hold (t_{HLD}) and delay (t_{DL}) times.

 $t_{AP}\,t_{HLD}$ and t_{DL} are specified in the Electrical Characteristics table.

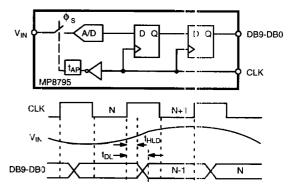


Figure 12. MP8795 Functional Equivalent Circuit and Interface Timing

Power Down

Figure 13. shows the relationship between the clock, sampled ${\sf A_{IN}}$ to output data relationship and the effect of power down.

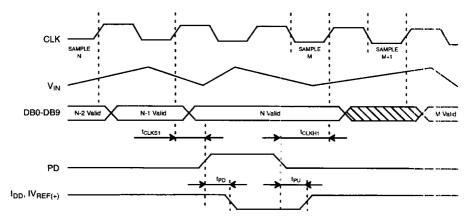


Figure 13. Power Down Timing Diagram



APPLICATION NOTES

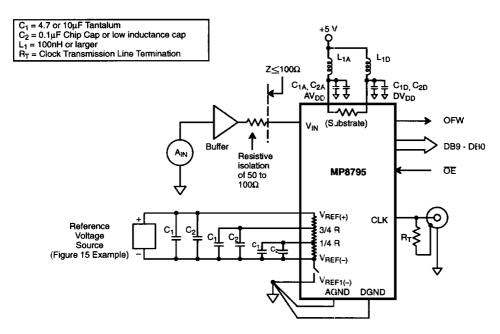


Figure 14. Typical Circuit Connections

The following information will be useful in maximizing the performance of the MP8795.

- All signals should not exceed AV_{DD} +0.5 V or AGND -0.5 V or DV_{DD} +0.5 V or DGND -0.5 V.
- Any input pin which can see a value outside the absolute maximum ratings (AV_{DD} or DV_{DD}+0.5 V or AGND –0.5 V) should be protected by diode clamps (HP5082-2835) from input pin to the supplies. All MP7684A inputs have input protection diodes which will protect the device from short transients outside the supply ranges.
- The design of a PC board will affect the accuracy of MP8795.
 Use of wire wrap is not recommended.
- The analog input signal (V_{IN}) is quite sensitive and should be properly routed and terminated. It should be shielded from the clock and digital outputs so as to minimize cross coupling and noise pickup.
- 5. The analog input should be driven by a low impedance (less than 50Ω).
- Analog and digital ground planes should be substantial and common at one point only. The ground plane should act as a

- shield for parasitics and not a return path for signals. To reduce noise levels, use separate low impedance ground paths. DGND should not be shared with other digital circuitry. If separate low impedance paths cannot be provided, DGND should be connected to AGND next to the MP8795.
- DV_{DD} should not be shared with other digital circuitry to avoid conversion errors caused by digital supply transients. DV_{DD} for the MP8795 should be connected to AV_{DD} next to the MP8795.
- DV_{DD} and AV_{DD} are connected inside the MP8795 through the N -- doped silicon substrate. Any E/C voltage difference between DV_{DD} and AV_{DD} will cause undesirable internal currents.
- Each power supply and reference voltage pin should be decoupled with a ceramic (0.1μF) and a tantalum (10μF) capacitor as close to the device as possible.
- 10. The digital output should not drive long wires. The capacitive coupling and reflection will contribute noise to the conversion. When driving distant loads, buffers should be used. 100Ω resistors in series with the digital outputs in some applications reduces the digital output disruption of A_{IN}.

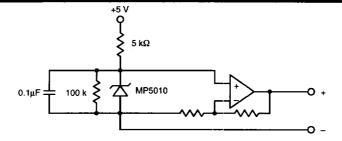
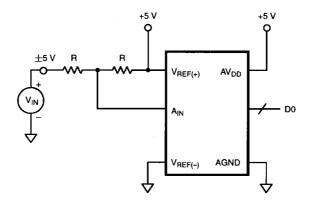


Figure 15. Example of a Reference Voltage Source



For R = 5k use Beckman Instruments #694-3-R10k resistor array or equivalent.

NOTE: High R values affect the input BW of ADC due to the (R * C_{IN} of ADC) time constant. Therefore, for different applications the R value needs to be selected as a tradeoff between A_{IN} settling time and power dissipator.

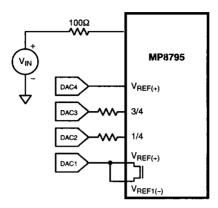
Figure 16. ±5 V Analog Input

For R = 5k use Beckman Instruments #694-3-R10k resistor array or equivalent.

NOTE: High R values affect the input BW of ADC due to the (R \star C $_{\rm IN}$ of ADC) time constant. Therefore, for different applications the R value needs to be selected as a tradeoff between A $_{\rm IN}$ settling time and power dissipation.

Figure 17. ±10 V Analog Input





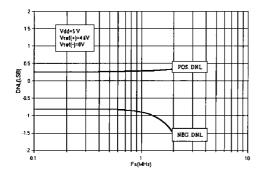
DACs MP7226 or MP7641

@ Power Down write values to DAC 3, 2, 1 = DAC 4 to minimize power consumption.
Only A_{IN} and Ladder detail shown.

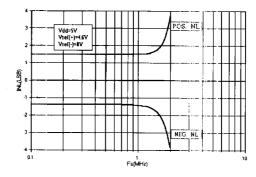
Figure 18. A/D Ladder with Programmed Control (of V_{REF(+)}, V_{REF(-)}, 1/4 and 3/4 TAP.)



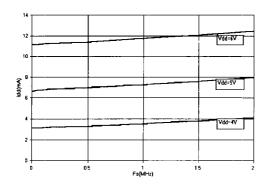
PERFORMANCE CHARACTERISTICS



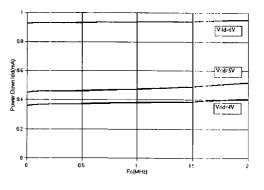
Graph 1. DNL vs. Sampling Frequency



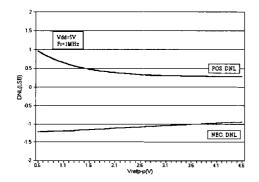
Graph 2. INL vs. Sampling Frequency



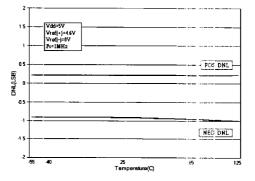
Graph 3. Supply Current vs. Sampling Frequency



Graph 4. Power Down Current vs. Sampling Frequency

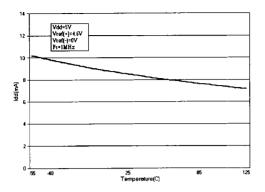


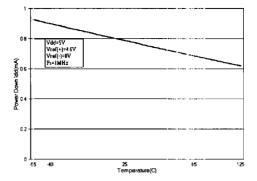
Graph 5. DNL vs. Reference Voltage



Graph 6. DNL vs. Temperature

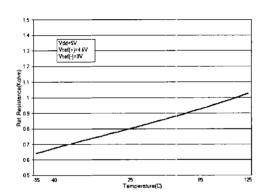






Graph 7. Supply Current vs. Temperature

Graph 8. Power Down Current vs. Temperature



Graph 9. Reference Resistance vs. Temperature